



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Jason M. Benz

Serial No.: 09/695,028

Group Art Unit: 1765

Filed: October 24, 2000

Examiner: Alanko, Anita K.

For: METHOD FOR THIN FILM LASER REFLECTANCE CORRELATION FOR  
SUBSTRATE ETCH ENDPOINT

**EXCESS CLAIM FEE PAYMENT LETTER**

Sir:

Transmitted herewith is an amendment in the above-identified application. The fee has been calculated and is transmitted as shown below.

	<u>AFTER AMENDMENT</u>	<u>PREV. PAID FOR</u>	<u>EXTRA CLAIMS PRESENT</u>	<u>RATE</u>	<u>FEES DUE</u>
Total Claims	33	-	= 3	x \$18.00	\$ 54.00
Indep. Claims	3	-	= 0	x \$84.00	\$ .00
<b>TOTAL ADDITIONAL FEE FOR THIS AMENDMENT</b>					<b>\$ 54.00</b>

Please charge Assignee's Deposit Account No. 09-0456 in the amount of \$ 54.00 to cover the excess claim fees. A duplicate copy of this sheet is enclosed. The Commissioner is authorized to charge any deficiencies in fees and credit any overpayment of fees to Assignee's Deposit Account No. 09-0456.

Respectfully Submitted,

Sean M. McGinn  
Reg. No. 34,386

Date: 10/21/02

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Honorable Commissioner of Patents  
Washington, D.C. 20231

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AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated July 8, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

10/10/2002 EHAILE1 00000028 090456 09695028  
01 FC:103 54.00 CH

Please amend the claims as follows:

*B1* 1. (Amended) A method of etching a substrate, comprising:  
2       measuring a reflectance signal from a reflective material deposited on said substrate as  
3       the substrate is being etched;  
4       correlating the substrate etch rate to the reflectance signal from the reflective material;  
5       and  
6       using the etch relation between the substrate and the reflective material to determine  
7       the etch target,  
8       wherein said reflective material is isolated from an etching process.

*B2D3* 2. (Amended) The method of claim 1, wherein said reflective material comprises metal  
having a metal oxide thereon, and said substrate etch also etches said metal oxide on said